

Electronic Patent Application Fee Transmittal

Application Number:	10500381			
Filing Date:	29-Jun-2004			
Title of Invention:	SOI WAFER MANUFACTURING METHOD AND SOI WAFER			
First Named Inventor/Applicant Name:	Masatake Nakano			
Filer:	Christopher W. Brown/Roberta Vahey			
Attorney Docket Number:	120164			
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